



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

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## Product Summary

$V_{(BR)DSS}$	$R_{DS(ON) \max}$	$I_D \max$ $T_A = +25^\circ\text{C}$
30V	14m $\Omega$ @ $V_{GS} = 10\text{V}$	10A
	20m $\Omega$ @ $V_{GS} = 4.5\text{V}$	8A

## Features and Benefits

- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed

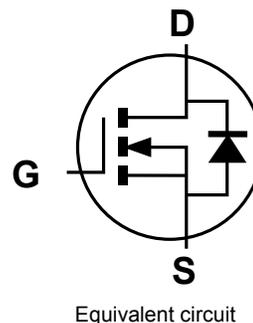
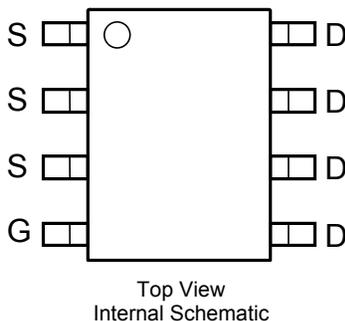
## Description and Applications

This MOSFET has been designed to minimize the on-state resistance ( $R_{DS(on)}$ ) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Backlighting
- Power Management Functions
- DC-DC Converters

## Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Weight: 0.072 grams (approximate)



**Maximum Ratings** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			$V_{DS}$	30	V
Gate-Source Voltage			$V_{GS}$	$\pm 20$	V
Continuous Drain Current (Note 5)	Steady State	$T_A = +25^\circ\text{C}$	$I_D$	10	A
		$T_A = +70^\circ\text{C}$		9	
Pulsed Drain Current (10 $\mu\text{s}$ pulse, duty cycle = 1%)			$I_{DM}$	50	A

**Thermal Characteristics**

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	$P_D$	1.52	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	82	$^\circ\text{C/W}$
Thermal Resistance, Junction to Case (Note 6)	$R_{\theta JC}$	8.2	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS (Note 6)</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	30	—	—	V	$V_{GS} = 0V, I_D = 250\mu\text{A}$
Zero Gate Voltage Drain Current $T_J = +25^\circ\text{C}$	$I_{DSS}$	—	—	1.0	$\mu\text{A}$	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Source Leakage	$I_{GSS}$	—	—	$\pm 100$	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
<b>ON CHARACTERISTICS (Note 6)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	1.05	—	1.95	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(on)}$	—	11	14	m $\Omega$	$V_{GS} = 10V, I_D = 11.6A$
			15	20		$V_{GS} = 4.5V, I_D = 10A$
Forward Transfer Admittance	$ Y_{fs} $	—	8	—	S	$V_{DS} = 5V, I_D = 11.6A$
Diode Forward Voltage	$V_{SD}$	—	0.73	0.95	V	$V_{GS} = 0V, I_S = 1A$
<b>DYNAMIC CHARACTERISTICS (Note 7)</b>						
Input Capacitance	$C_{iss}$	—	867	—	pF	$V_{DS} = 10V, V_{GS} = 0V,$ $f = 1.0\text{MHz}$
Output Capacitance	$C_{oss}$	—	85	—	pF	
Reverse Transfer Capacitance	$C_{rss}$	—	81	—	pF	
Gate Resistance	$R_g$	—	1.39	—	$\Omega$	$V_{DS} = 0V, V_{GS} = 0V, f = 1\text{MHz}$
Total Gate Charge	$Q_g$	—	18.85	—	nC	$V_{GS} = 10V, V_{DS} = 15V,$ $I_D = 11.6A$
Gate-Source Charge	$Q_{gs}$	—	2.59	—	nC	
Gate-Drain Charge	$Q_{gd}$	—	6.15	—	nC	
Turn-On Delay Time	$t_{D(on)}$	—	5.46	—	ns	$V_{DD} = 15V, V_{GS} = 10V,$ $R_L = 1.3\Omega, R_G = 3\Omega, I_D = 1A$
Turn-On Rise Time	$t_r$	—	14.53	—	ns	
Turn-Off Delay Time	$t_{D(off)}$	—	18.84	—	ns	
Turn-Off Fall Time	$t_f$	—	6.01	—	ns	

- Notes:
- Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
  - Short duration pulse test used to minimize self-heating effect.
  - Guaranteed by design. Not subject to product testing.

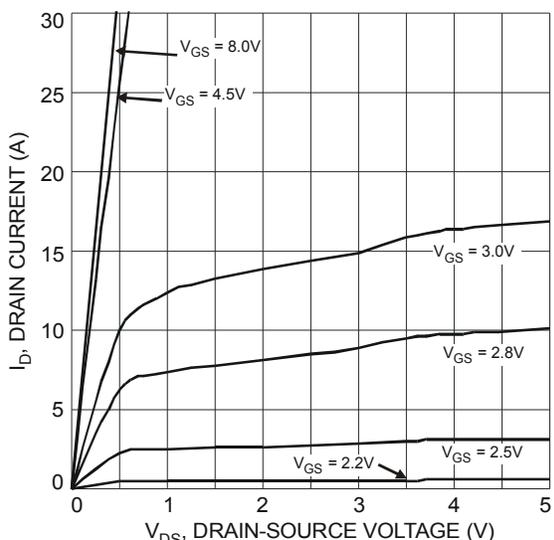


Fig. 1 Typical Output Characteristic

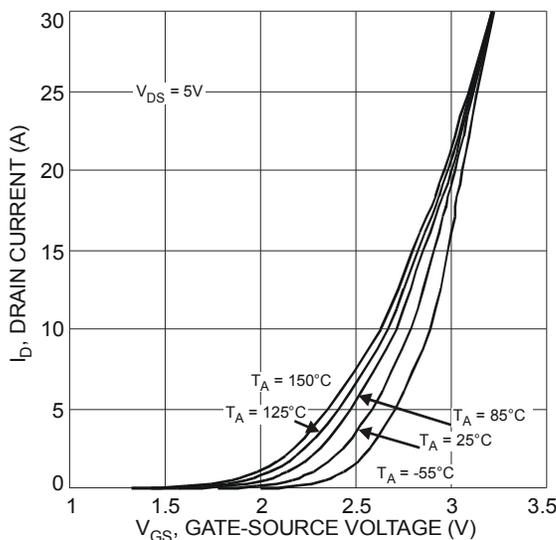


Fig. 2 Typical Transfer Characteristic

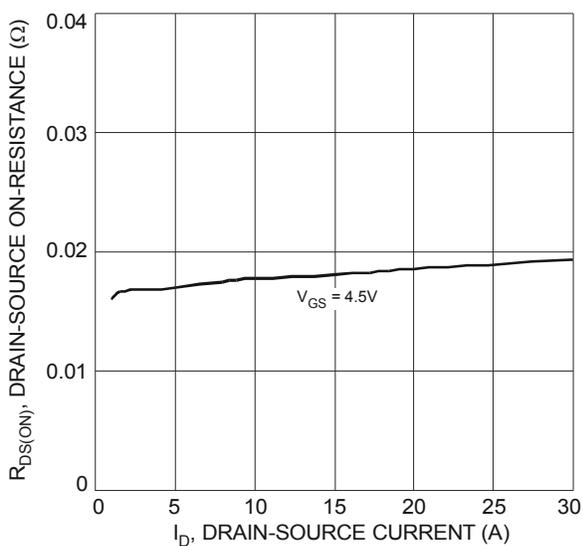


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

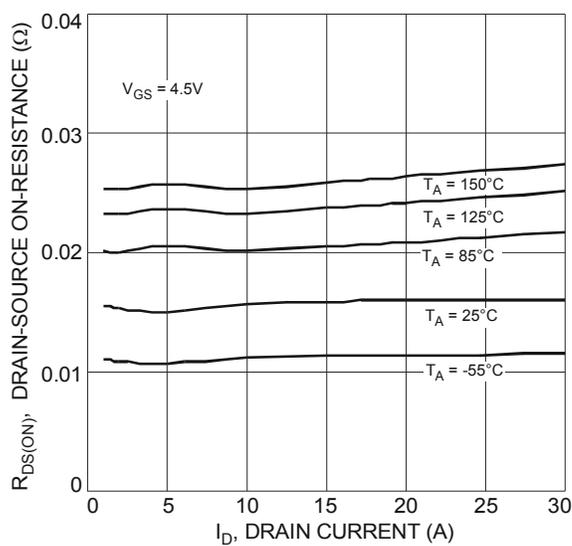


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

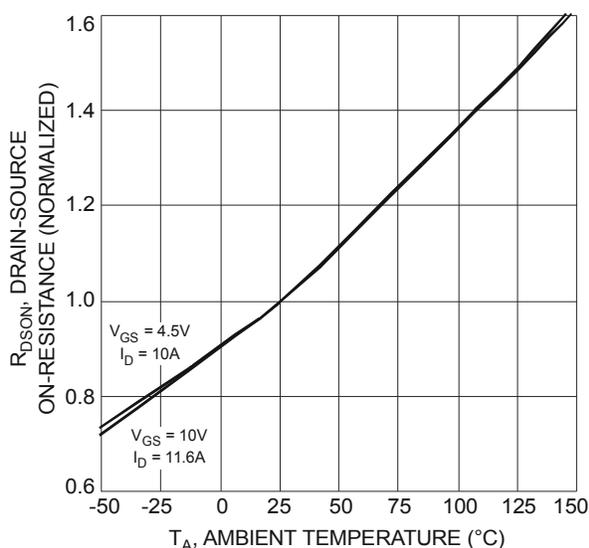


Fig. 5 On-Resistance Variation with Temperature

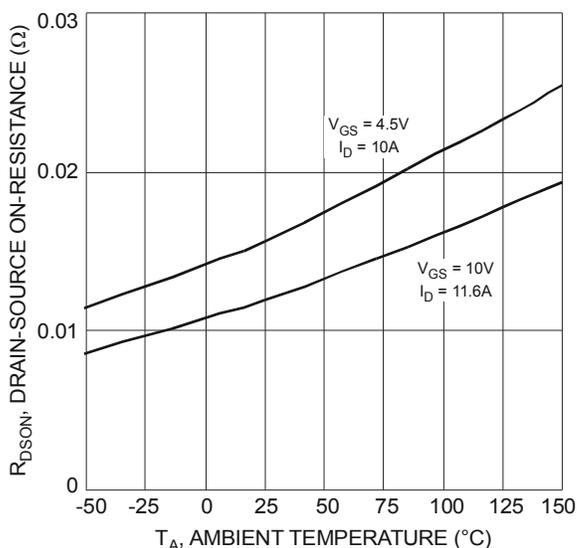


Fig. 6 On-Resistance Variation with Temperature

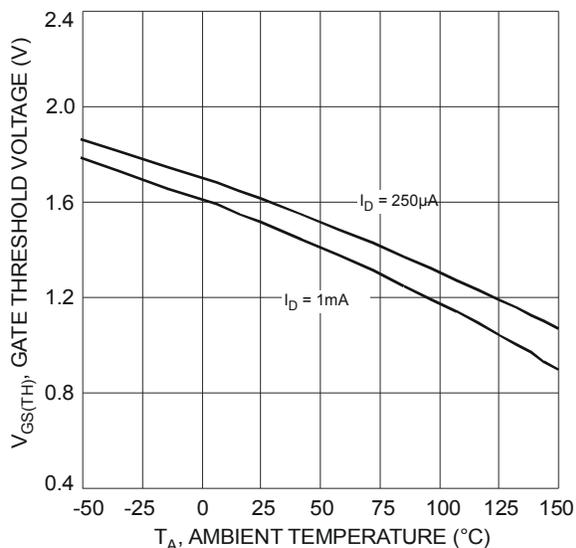


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

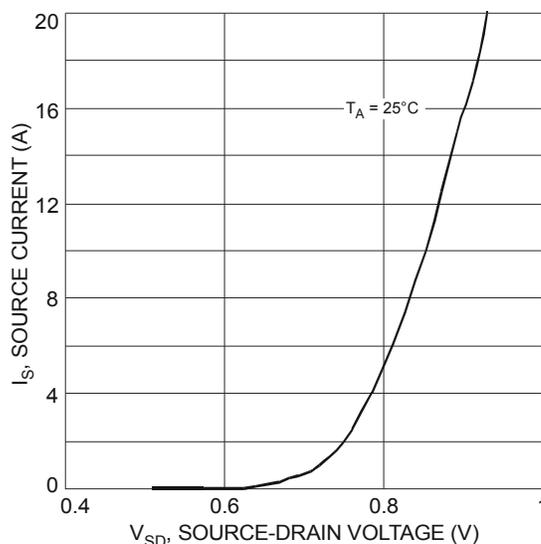


Fig. 8 Diode Forward Voltage vs. Current

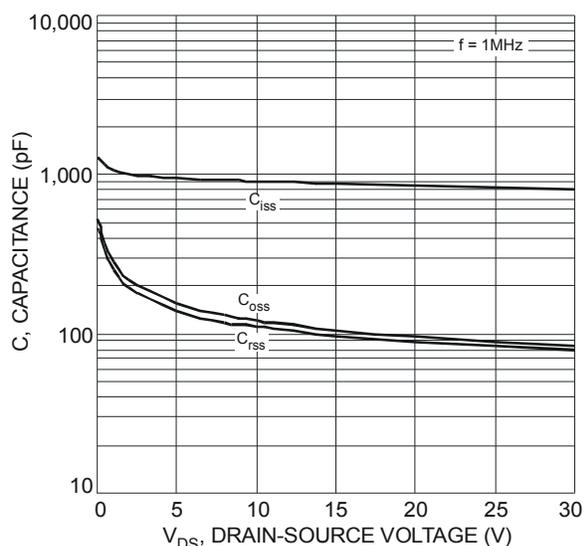


Fig. 9 Typical Total Capacitance

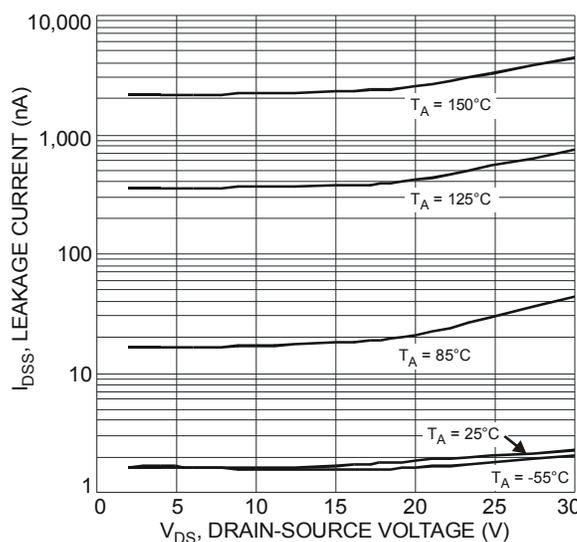


Fig. 10 Typical Leakage Current vs. Drain-Source Voltage

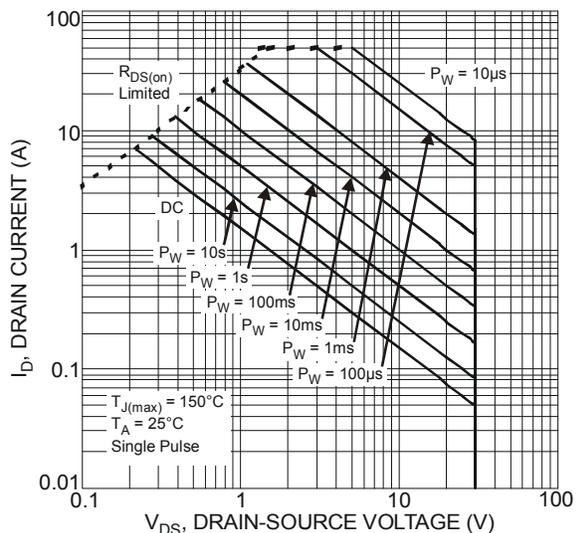


Fig. 11 SOA, Safe Operation Area

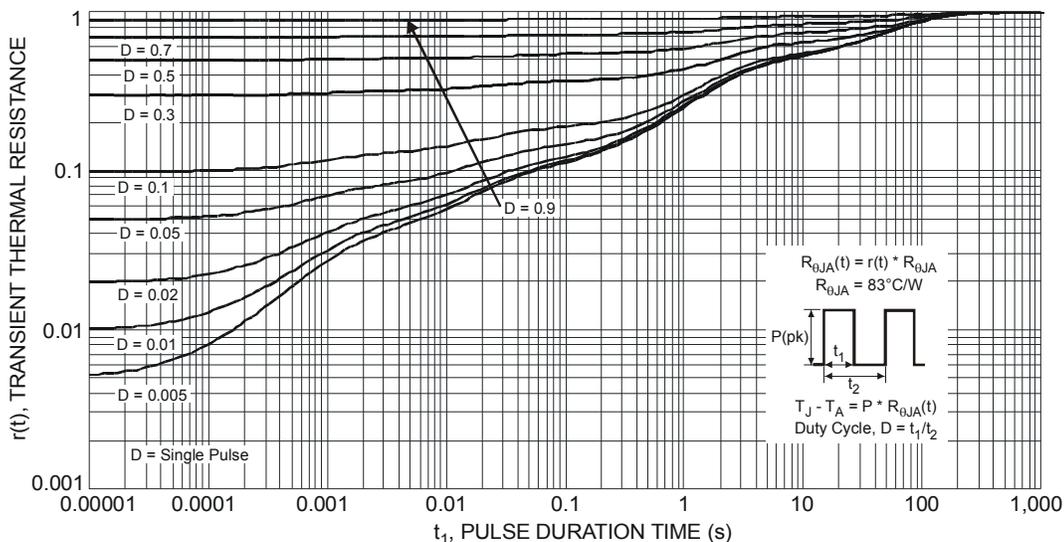
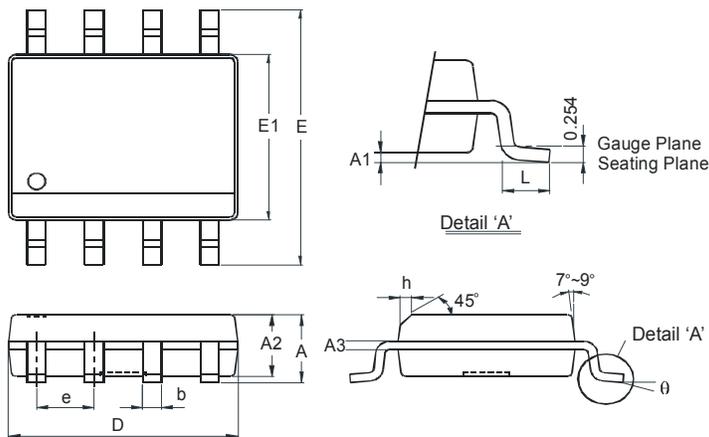


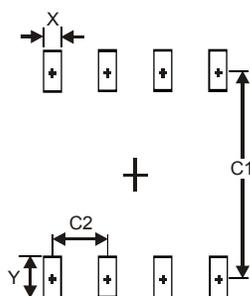
Fig. 12 Transient Thermal Response

**Package Outline Dimensions**



SO-8		
Dim	Min	Max
A	—	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	—	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

**Suggested Pad Layout**



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27